

outputting a first wafer sheet with a sugar content of at least 23% or an equivalent content of a sugar substitute from a baking oven at an elevated temperature;

7. Sub B¹ ~~cont~~ applying to the first wafer sheet, while the first wafer sheet is at the elevated temperature, a layer of a food product;

R1 providing a second wafer sheet with a sugar content of at least 23% or an equivalent content of a sugar substitute, and placing the second wafer sheet, while the second wafer sheet is at the elevated temperature, on the first wafer sheet; and

subsequently compressing the first and second wafer sheets and shaping the first and second wafer sheets containing the layer of the food product at the elevated temperature.

Claim 2 (amended). The method according to claim 1, which comprises placing onto the first wafer sheet the food product selected from the group consisting of a confection, meat product, fish product, cheese product, fruit product, vegetable product, nuts, and almonds.

Claim 3 (amended). The method according to claim 1, wherein the sugar substitute is trehalose.

Sub B² ~~cont~~ Claim 5 (amended). The method according to claim 1, which comprises, subsequent to the pressing step, cutting the shaped

Sub B3 cont. *R2*
wafer product into individual wafer products and providing the individual wafer products with an outer coating.

Claim 6 (amended). The method according to claim 1, which comprises processing, together with the first and second wafer sheets, additional wafer sheets at the elevated temperature with interposed layers of food products.